

### 1. General description

PNP low V<sub>CEsat</sub> transistor in DFN2020D-3 (SOT1061D) leadless small Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

NPN complement: PBSS4350PAS

### 2. Features and benefits

- DFN2020D-3 (SOT1061D) package
- Low collector-emitter saturation voltage V<sub>CEsat</sub>
- High collector current capability: I<sub>C</sub> and I<sub>CM</sub>
- Higher efficiency leading to less heat generation
- Reduced printed-circuit board requirements
- Leadless small SMD plastic package with solderable side pads
- Exposed heat sink for excellent thermal and electrical conductivity
- Suitable for Automatic Optical Inspection (AOI) of solder joint

### 3. Applications

- Loadswitch
  - Battery-driven devices
  - Power management
  - · Charging circuits
  - Power switches (e.g. motors, fans)

### 4. Quick reference data

Table 1. Quick	reference data					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>CEO</sub>	collector-emitter voltage	open base	-	-	-50	V
I <sub>C</sub>	collector current		-	-	-3	A
I <sub>CM</sub>	peak collector current	limited by T <sub>j(max)</sub>	-	-	-5	A
R <sub>CEsat</sub>	collector-emitter saturation resistance	$I_C$ = -2 A; $I_B$ = -200 mA; pulsed; $t_p$ ≤ 300 μs; δ ≤ 0.02; $T_{amb}$ = 25 °C	-	90	135	mΩ

# nexperia

# 5. Pinning information

Table 2	. Pinning info	ormation		
Pin	Symbol	Description	Simplified outline	Graphic symbol
1	В	base	3	
2	E	emitter		с
3	C	collector	I 2   Transparent top view   DFN2020D-3 (SOT1061D)	B E sym132

# 6. Ordering information

Table 3. Ordering	information
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Type number			
	Name	Description	Version
PBSS5350PAS		plastic, leadless thermal enhanced ultra thin small outline package with side-wettable flanks (SWF); no leads; 3 terminals; 1.3 mm pitch; 2 mm x 2 mm x 0.65 mm body	<u>SOT1061D</u>

# 7. Marking

Table 4. Marking codes	
Type number	Marking code
PBSS5350PAS	G4

### 8. Limiting values

#### Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>CBO</sub>	collector-base voltage	open emitter		-	-50	V
V <sub>CEO</sub>	collector-emitter voltage	open base		-	-50	V
V <sub>EBO</sub>	emitter-base voltage	open collector		-	-5	V
I <sub>C</sub>	collector current			-	-3	А
I <sub>CM</sub>	peak collector current	limited by T <sub>j(max)</sub>		-	-5	А
I <sub>B</sub>	base current			-	-0.5	А
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[1]	-	0.5	W
			[2] [3]	-	1	W
			[4]	-	1.2	W
			[5] [6]	-	2	W
Tj	junction temperature			-	150	°C
T <sub>amb</sub>	ambient temperature			-65	150	°C
T <sub>stg</sub>	storage temperature			-65	150	°C

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

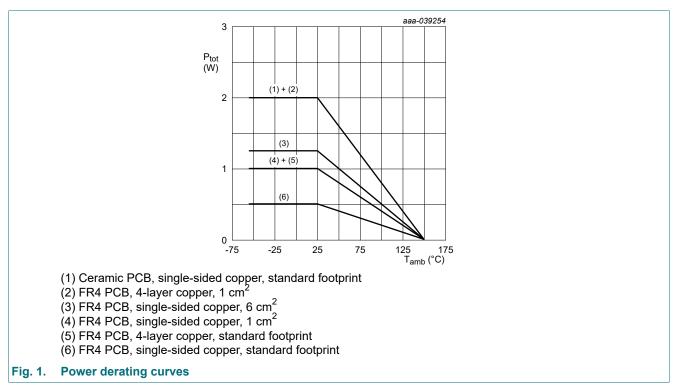
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.

[3] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and standard footprint.

[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm<sup>2</sup>.

[5] Device mounted on a ceramic PCB,  $AI_2O_3$ , standard footprint.

[6] Device mounted on a FR4 PCB, 4-layer copper, tin-plated and mounting pad for collector 1 cm<sup>2</sup>.



### 9. Thermal characteristics

#### Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Тур	Мах	Unit
R <sub>th(j-a)</sub> thermal resistance from junction to ambient		[1]	-	-	250	K/W	
		[2] [3]	-	-	125	K/W	
		[4]	-	-	100	K/W	
			[5] [6]	-	-	60	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

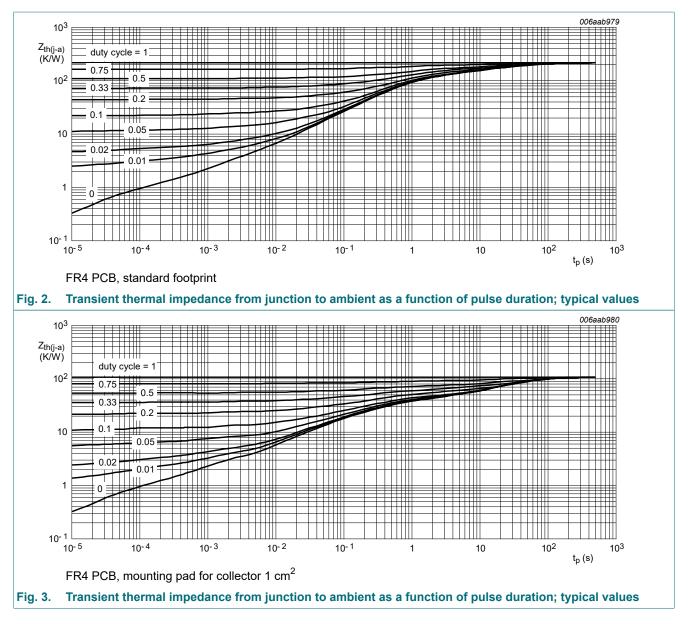
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.

[3] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and standard footprint.

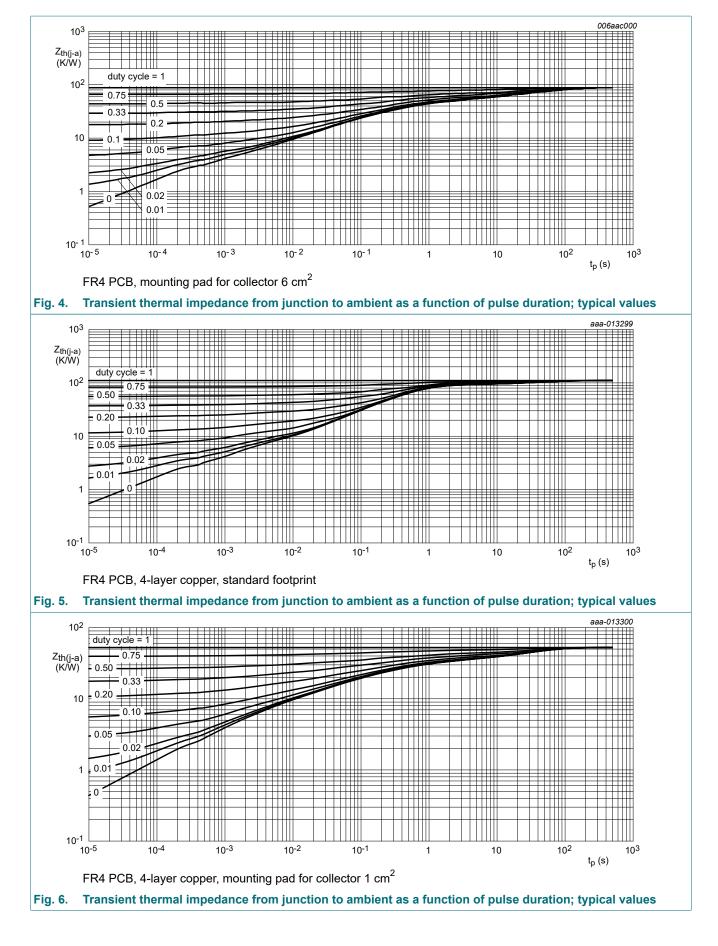
[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm<sup>2</sup>.

[5] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.

[6] Device mounted on a FR4 PCB, 4-layer copper, tin-plated and mounting pad for collector 1 cm<sup>2</sup>.

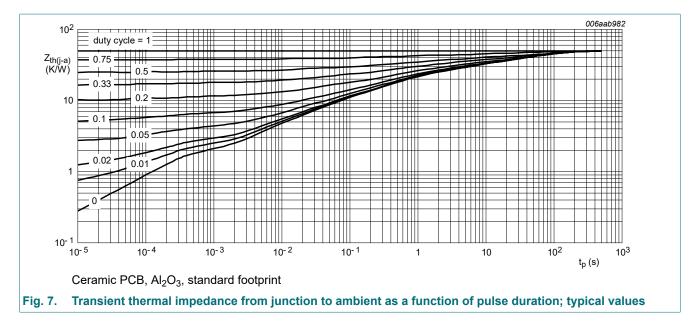


#### 50 V, 3 A PNP low VCEsat transistor



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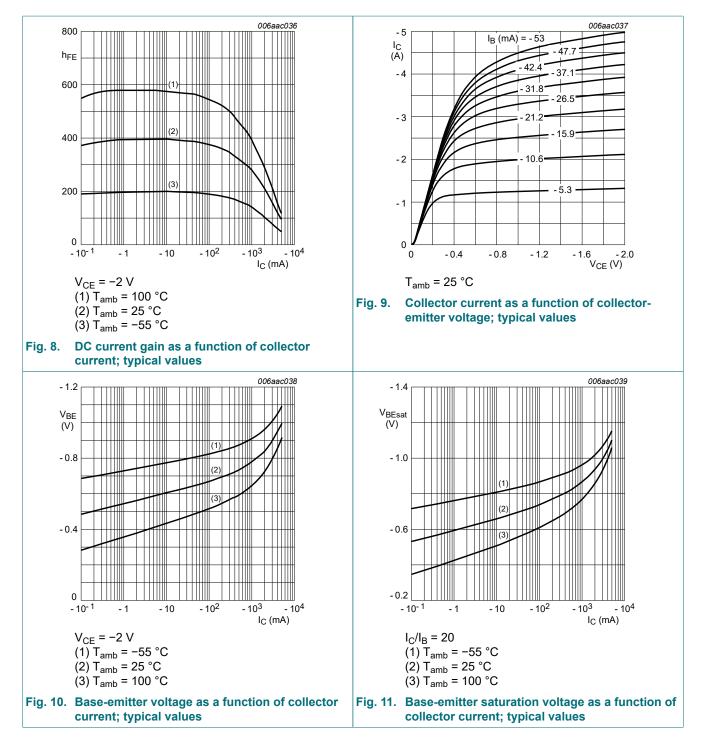
#### 50 V, 3 A PNP low VCEsat transistor



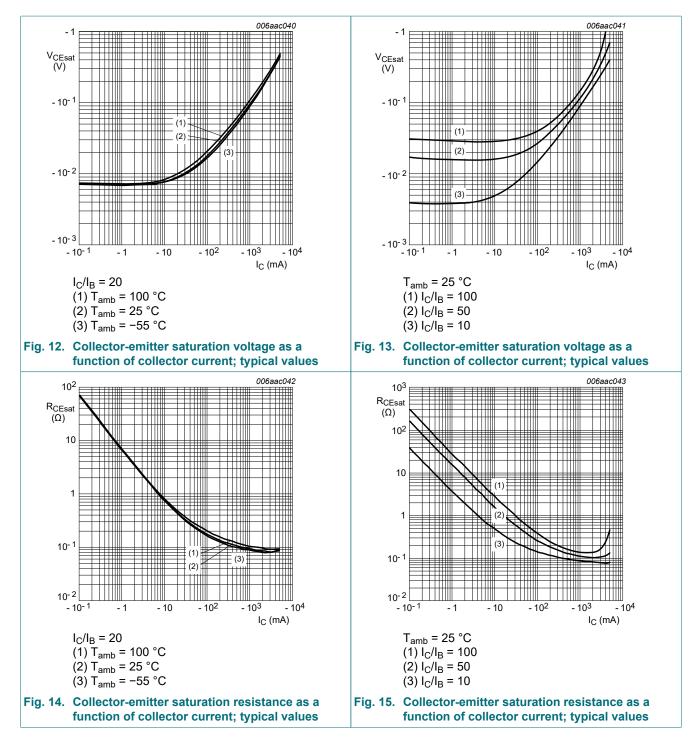
## **10. Characteristics**

Symbol	Parameter	Conditions	Min	Тур	Мах	Unit
V <sub>(BR)CBO</sub>	collector-base breakdown voltage	$I_{C}$ = -100 µA; $I_{E}$ = 0 A; $T_{amb}$ = 25 °C	-50	-	-	V
V <sub>(BR)CEO</sub>	collector-emitter breakdown voltage	I <sub>C</sub> = -10 mA; I <sub>B</sub> = 0 A; T <sub>amb</sub> = 25 °C	-50	-	-	V
V <sub>(BR)EBO</sub>	emitter-base breakdown voltage	I <sub>E</sub> = -100 μA; I <sub>C</sub> = 0 A; T <sub>amb</sub> = 25 °C	-5	-	-	V
I <sub>CBO</sub>	collector-base cut-off	$V_{CB}$ = -50 V; I <sub>E</sub> = 0 A; T <sub>amb</sub> = 25 °C	-	-	-100	nA
	current	V <sub>CB</sub> = -50 V; I <sub>E</sub> = 0 A; T <sub>j</sub> = 150 °C	-	-	-50	μA
I <sub>CES</sub>	collector-emitter cut-off current	$V_{CE}$ = -50 V; $V_{BE}$ = 0 V; $T_{amb}$ = 25 °C	-	-	-100	nA
I <sub>EBO</sub>	emitter-base cut-off current	V <sub>EB</sub> = -5 V; I <sub>C</sub> = 0 A; T <sub>amb</sub> = 25 °C	-	-	-100	nA
h <sub>FE</sub> DC cu	DC current gain	$V_{CE}$ = -2 V; I <sub>C</sub> = 0.1 A; single pulse; t <sub>p</sub> ≤ 300 µs; $\delta$ ≤ 0.02; T <sub>amb</sub> = 25 °C	200	-	-	
		V <sub>CE</sub> = -2 V; I <sub>C</sub> = -0.5 A; pulsed; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>amb</sub> = 25 °C	200	-	-	
		$V_{CE}$ = -2 V; I <sub>C</sub> = -1 A; pulsed; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>amb</sub> = 25 °C	200	-	450	
		$V_{CE}$ = -2 V; I <sub>C</sub> = -2 A; pulsed; t <sub>p</sub> ≤ 300 µs; $\delta$ ≤ 0.02; T <sub>amb</sub> = 25 °C	130	-	-	
		$V_{CE}$ = -2 V; I <sub>C</sub> = -3 A; pulsed; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>amb</sub> = 25 °C	80	-	-	
V <sub>CEsat</sub>	collector-emitter	I <sub>C</sub> = -0.5 A; I <sub>B</sub> = -50 mA; T <sub>amb</sub> = 25 °C	-	-	-90	mV
	saturation voltage	I <sub>C</sub> = -1 A; I <sub>B</sub> = -50 mA; T <sub>amb</sub> = 25 °C	-	-	-180	mV
		$I_{C}$ = -2 A; $I_{B}$ = -100 mA; $T_{amb}$ = 25 °C	-	-	-320	mV
		$I_{C}$ = -2 A; $I_{B}$ = -200 mA; pulsed; $t_{p} \le$ 300 μs; δ ≤ 0.02; $T_{amb}$ = 25 °C	-	-	-270	mV
		I <sub>C</sub> = -3 A; I <sub>B</sub> = -300 mA; pulsed; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>amb</sub> = 25 °C	-	-	-390	mV
R <sub>CEsat</sub>	collector-emitter saturation resistance	I <sub>C</sub> = -2 A; I <sub>B</sub> = -200 mA; pulsed; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>amb</sub> = 25 °C	-	90	135	mΩ
V <sub>BEsat</sub>	base-emitter saturation	I <sub>C</sub> = -2 A; I <sub>B</sub> = -100 mA; T <sub>amb</sub> = 25 °C	-	-	-1.1	V
	voltage	I <sub>C</sub> = -3 A; I <sub>B</sub> = -300 mA; pulsed; t <sub>p</sub> ≤ 300 μs; δ ≤ 0.02; T <sub>amb</sub> = 25 °C	-	-	-1.2	V
V <sub>BE</sub>	base-emitter voltage	V <sub>CE</sub> = -2 V; I <sub>C</sub> = -1 A; T <sub>amb</sub> = 25 °C	-	-	-1.1	V
f <sub>T</sub>	transition frequency	V <sub>CE</sub> = -5 V; I <sub>C</sub> = -100 mA; f = 100 MHz; T <sub>amb</sub> = 25 °C	100	-	-	MHz
C <sub>c</sub>	collector capacitance	V <sub>CB</sub> = -10 V; I <sub>E</sub> = 0 A; i <sub>e</sub> = 0 A; f = 1 MHz; T <sub>amb</sub> = 25 °C	-	-	35	pF

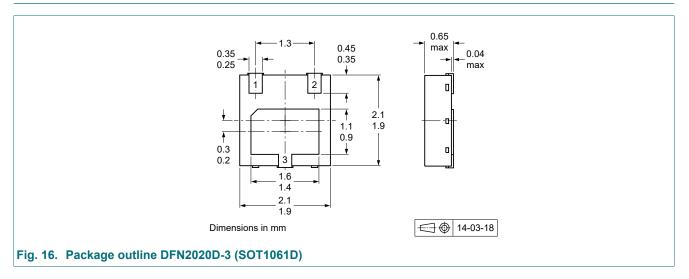
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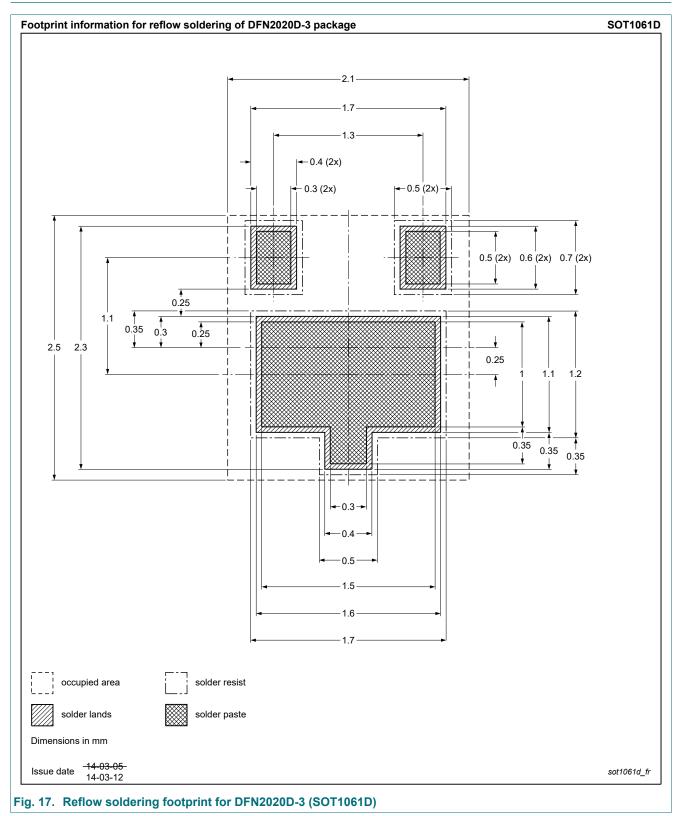
#### 50 V, 3 A PNP low VCEsat transistor



# 11. Package outline



### 12. Soldering



# 13. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PBSS5350PAS v.2	20240807	Product data sheet	-	PBSS5350PAS v.1
Modifications:	<ul><li>Graphic symbol</li><li>Characteristics g</li></ul>	corrected. graphs are changed.		
PBSS5350PAS v.1	20240516	Product data sheet	-	-

#### 50 V, 3 A PNP low VCEsat transistor

### 14. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

 Please consult the most recently issued document before initiating or completing a design.

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